

SPECIFICATION

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SPECIFICATION

Model No:

RET012864DYPP3N00000

CUSTOMER:

APPROVED BY
PCB VERSION
DATE
FOR CUSTOMER USE ONLY
SALES BY
APPROVED BY
CHECKED BY
PREPARED BY
Release DATE:



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1. Revision History

DATE	VERSION	REVISED PAGE NO.	Note
2011/11/8	1		First release
2012/09/24	2	14	Add Power Consumption
		15	Add Optics Characteristics
		21	Modify picture
2013/01/09	3	16	Add Mechanical Test
2013/01/16	4	16	Add note
		9	R1_a=1M ohm
		15	Add CIE chromaticity
			diagram
2014/01/27	5		Update Rev.

2. General Specification

The Features is described as follow:

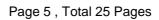
- Module dimension: 73.00 x 41.86 x 2.0 (max.) mm
- Active area: 61.41 x 30.69 mm
- Dot Matrix: 128 x 64
- Dot Size: 0.45 x 0.45mm
- Dot Pitch: 0.48 x 0.48mm
- Display Mode: Passive Matrix
- Duty: 1/64
 - Display Color: Monochrome (Yellow)



3. Module Coding System

1	2	3	4	5	6	7	8	9	10	11	12	13
R	E	Т	012864	D	Y	Р	Р	3	Ν	0	0	000

ltem	Description		
1	R : Raystar Optron	lics Inc.	
2	E : OLED		
3	Display Type: C→C	Character Type, G→Graphic Ty	pe, T→TAB Type
4	Dot Matrix : 128 Do	ots x 64 Dots	
5	Serials code		
		A : Amber	R : RED
6	Emitting Color	B : Blue	Y : Yellow
		G : Green	W:White
7	Polarizer	P: With Polarizer; N: Without	ut Polarizer
8	Display Mode	P: Passive Matrix ; A: Active	e Matrix
9	Driver Voltage	3: 3.0 V; 5: 5.0V	
10	Touch Panel	N: Without touch panel; T:	With touch panel
11	Species	0:Normal, 1:Sunlight readabl	e, 2:Transparent, 3:Flexible,
	•	4:Lighting	
12	Grade code		
13	Serial No.	000: Sales code	



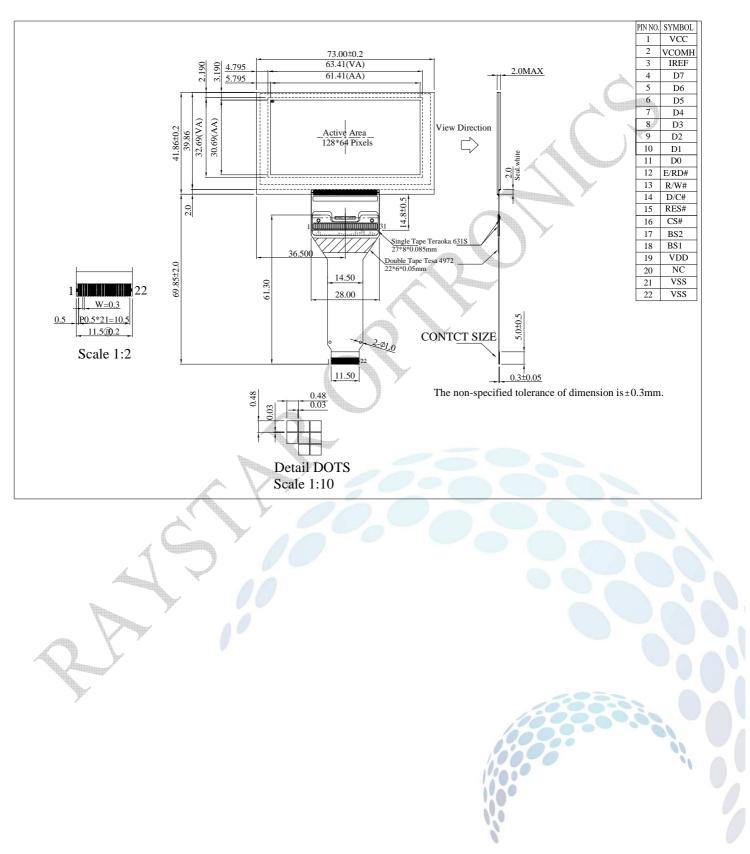


4. Interface Pin Function

No.	Symbol	Function					
1	VCC	Power supply for analog circuit.					
2	VCOMH	Com Voltage Output. A capacitor should be obstructed by between this pin and VSS.	connected				
3	IREF	Reference current input pin. A resistor should be connected between this	pin and VSS.				
4~11	D7~D0	Data bus.					
12	E/RD#	Data read operation is initiated when it's pull	low.				
13	R/W#	Data write operation is initiated when it's pull	low.				
14	D/C#	Data/ Command control. Pull high for write/read display data. Pull low for write command or read status.					
15	RES#	Reset signal input. When it's low, initialization of SSD1305 is exc	ecuted.				
16	CS#	Chip select input.					
17	BS2	Communicating Protocol Select These pins are MCU interface selection input following table:	t. See the				
18	BS1	I2C68XX-parall el80XX-paralleBS1101BS2011	I Serial 0 0				
19	VDD	Power supply for logic circuit.					
20	NC	No connection.					
21	VSS	Ground.					
22	VSS	Ground.					

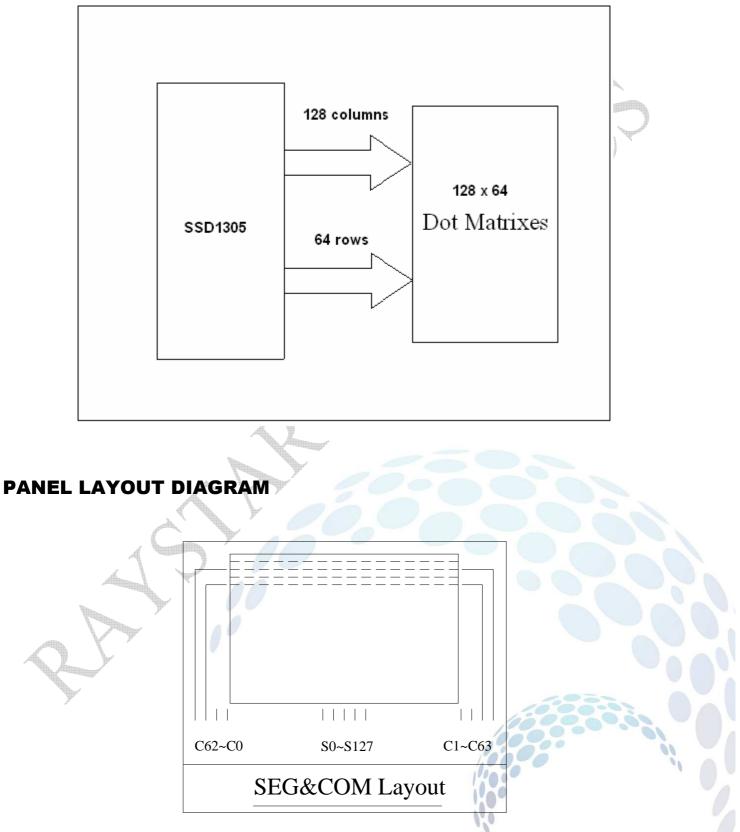


5. Outline Dimension & Block Diagram





FUNCTION BLOCK DIAGRAM



*For more information, please refer to Application Note provided by Raystar Optronics.

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6. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit	Notes
Supply Voltage for Logic	VDD	-0.3	3.5	V	1,2
Supply Voltage for Display	VCC	0	15	V	1,2
Operating Temperature	TOP	-40	80	C	-
Storage Temperature	TSTG	-40	80	C	

Note 1: All the above voltages are on the basis of "VSS = 0V".

Note 2: When this module is used beyond the above absolute maximum ratings, permanent breakage of the module may occur. Also, for normal operations, it is desirable to use this module under the conditions according to Section7 "Electrical Characteristics". If this module is used beyond these conditions, malfunctioning of the module can occur and the reliability of the module may deteriorate



7. Electrical Characteristics

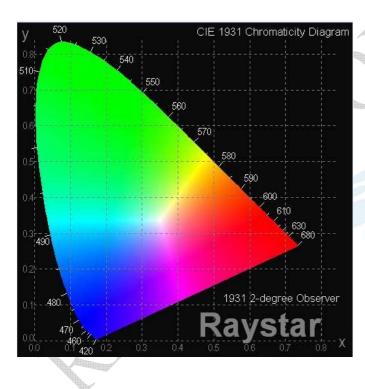
Item	Symbol	Condition	Min	Тур	Мах	Unit
Supply Voltage for Logic	VDD		2.8	3.0	3.3	V
Supply Voltage for Display	VCC		10	12	15	V
High Level Input	VIH		0.8×VDD	_	VDD	V
Low Level Input	VIL		0		0.2×VDD	V
High Level Output	VOH		0.9×VDD	-	VDD	V
Low Level Input	VOL		0		0.1×VDD	V
50% Check Board Operatin	g Current	VCC =12V	26	28	32	mA

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8. Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V)θ		160		A	deg
view vingie	(H)φ		160		5	deg
Contrast Ratio	CR	Dark	2000:1		$\left(- \right)$	-
Response Time	T rise	—		10		μs
	T fall		4	10		μs
Display with 50% check Board Brightness				80		cd/m2
CIEx(Yellow)		(CIE1931)	0.45	0.47	0.49	
CIEy(Yellow)		(CIE1931)	0.48	0.50	0.52	





9. OLED Lifetime

ITEM	Conditions	Min	Тур	Remark
Operating	Ta=25 ℃	80,000	100,000	Note
Life Time	/ Typical Brightness Value	Hrs	Hrs	NOLE

Note:

1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.

- 2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
- 3. Screen saving mode will extend OLED lifetime.



10. Reliability

Content of Reliability Test

Environmenta	l Test		
Test Item	Content of Test	Test Condition	Applicable Standard
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80℃ 240hrs	
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	80℃ 240hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-40℃ 240hrs	
High Temperature/ Humidity Storage	Endurance test applying the high temperature and high humidity storage for a long time.	60℃,90%RH 240hrs	
Temperature Cycle	Endurance test applying the low and high temperature cycle. -40°C 25°C 80°C 30min 5min 30min 1 cycle	-40°C/80°C 100 cycles	
Mechanical Te	st		
Vibration test	Endurance test applying the vibration during transportation and using.	10~22Hz→1.5mmp-p 22~500Hz→1.5G Total 0.5hr	
Shock test	Constructional and mechanical endurance test applying the shock during transportation.	50G Half sin wave 11 ms 3 times of each direction	
Atmospheric pressure test	Endurance test applying the atmospheric pressure during transportation by air.	115mbar 40hrs	
Others		•	
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5kΩ CS=100pF 1 time	

* Supply voltage for OLED module =Operating voltage at 25 $^\circ\!\mathrm{C}$



Test and measurement conditions

- All measurements shall not be started until the specimens attain to temperature stability. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5℃; 55±15% RH.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

Evaluation criteria

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within \pm 50% of initial value.

APPENDIX:

RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.



11. Inspection specification

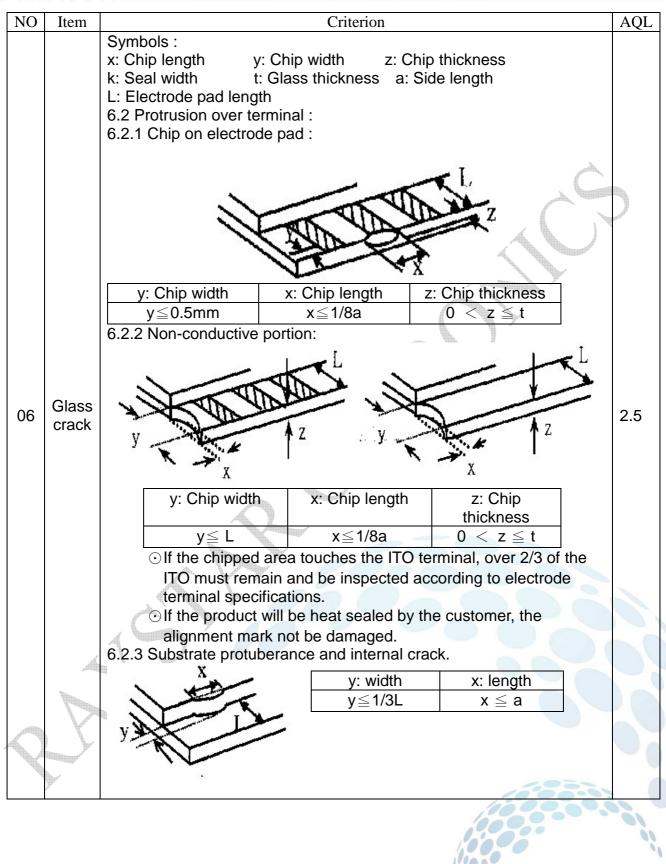
NO	Item	Criterion				AQL
01	Electrical Testing	defect. 1.2Missing cha 1.3Display mal 1.4No function	racter , d function. or no dis sumption gle defect uct types.	play. exceeds product		0.65
02	Black or white spots (display only)	than three w	white or b	ts on display $≤$ 0.2 lack spots present more than two sp	t.	2.5
03	Black spots, white spots, contaminatio n	3.1 Round type Φ=(x + y) /	2			2.5
	(non-display)	3.2 Line type : ((As follow Length L≦3.0 L≦2.5 	ving drawing) Width W≦0.02 0.02 <w≦0.03 0.03<w≦0.05 0.05<w< td=""><td>Acceptable Q TY Accept no dense 2 As round type</td><td>2.5</td></w<></w≦0.05 </w≦0.03 	Acceptable Q TY Accept no dense 2 As round type	2.5
04	Polarizer bubbles	If bubbles are v judge using bla specifications, r easy to find, mu check in specify direction.	ck spot not ust	Size Φ $\Phi \le 0.20$ $0.20 < \Phi \le 0.50$ $0.50 < \Phi \le 1.00$ $1.00 < \Phi$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5



NO	Item	Crit	erion	AQL			
05	Scratches	Follow NO.3 Black spots, white spots, contamination					
		Symbols Define:x: Chip lengthy: Chip wk: Seal widtht: Glass tL: Electrode pad length:					
		6.1 General glass chip : 6.1.1 Chip on panel surface a	nd crack between panels:	Ċ			
		X y k					
		z: Chip thickness y: C	hip width	ıth			
	Chipped		ver viewing x≦1/8a area				
06	glass	1/2t <z≦2t e<="" not="" td=""><td>xceed 1/3k $x \leq 1/8a$</td><td>2.5</td></z≦2t>	xceed 1/3k $x \leq 1/8a$	2.5			
		⊙ If there are 2 or more chips6.1.2 Corner crack:	, x is total length of each chip).			
			F				
			hip width x: Chip leng	,th			
	4		ver viewing x≤1/8a area				
			xceed 1/3k x≦1/8a				
		⊙ If there are 2 or more chips chip.	, x is the total length of each				
	$\langle \cdot \rangle$						

0







NO	Item	Criterion		
07	Cracked glass	With extensive crack is not acceptable.		
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using Spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 		
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.		
10	PCB · COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 		
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65	

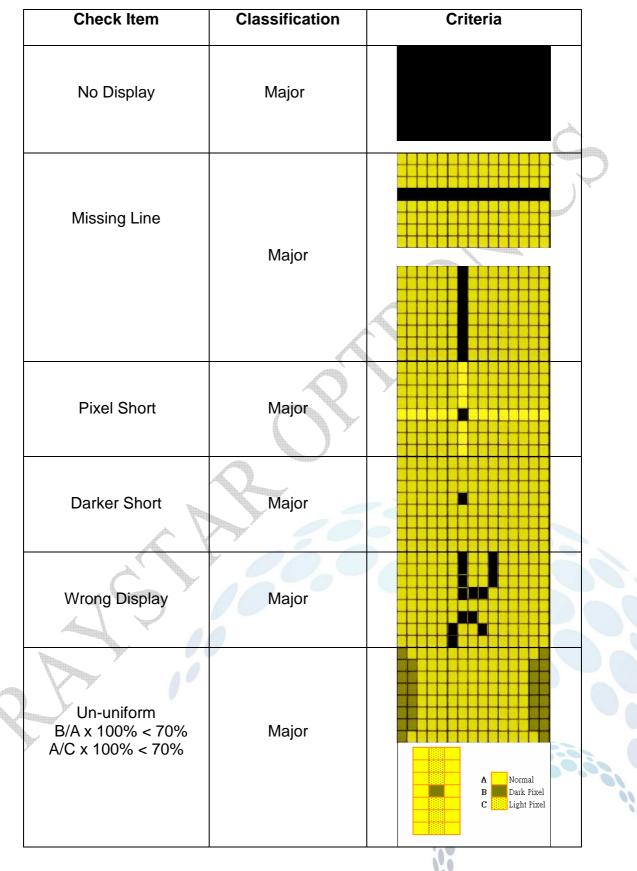
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NO	Item	Criterion	AQL
	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on	2.5
		product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the	
10		interface pin must be present or look as if it cause the interface pin to sever.	2.5
12		12.6 The residual rosin or tin oil of soldering (component or	2.5
		chip component) is not burned into brown or black color.	0.65
		12.7 Sealant on top of the ITO circuit has not hardened.	0.65
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 Pin loose or missing pins.	
		12.10 Product packaging must the same as specified on packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to	
		product specification sheet.	



Standard :





12. Precautions in use of Modules

- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of OLED display module.
- (3) Don't disassemble the OLED display module.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist OLED display module.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use fix information for long time in real application.
- (9) Don't use fixed information in OLED panel for long time, that will extend "screen burn" effect time..
- (10) Raystar has the right to change the passive components, including R2and R3 adjust resistors.(Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (11) Raystar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)

12.1 Handling Precautions

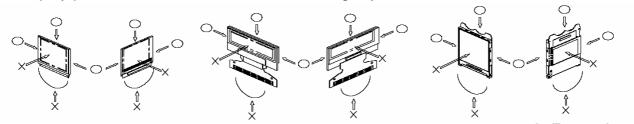
- (1) Since the display panel is being made of glass, do not apply mechanical impacts such us dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged and be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched. Please be careful when handling the OLED display module.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage of by using following adhesion tape.
- * Scotch Mending Tape No. 810 or an equivalent

Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent Also, pay attention that the following liquid and solvent may spoil the polarizer:

- * Water
- * Ketone
- * Aromatic Solvents



(6) Hold OLED display module very carefully when placing OLED display module into the System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.



- (7) Do not apply stress to the LSI chips and the surrounding molded sections.
- (8) Do not disassemble nor modify the OLED display module.
- (9) Do not apply input signals while the logic power is off.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
- * Be sure to make human body grounding when handling OLED display modules.
- * Be sure to ground tools to use or assembly such as soldering irons.
- * To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
- * Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.
- (11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (12) If electric current is applied when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.

12.2 Storage Precautions

- (1) When storing OLED display modules, put them in static electricity preventive bags avoiding exposure to direct sun light nor to lights of fluorescent lamps. And, also, avoiding high temperature and high humidity environment or low temperature (less than 0°C) environments.(We recommend you to store these modules in the packaged state when they were shipped from Raystar Optronics Inc. At that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them.
- (2) If electric current is applied when water drops are adhering to the surface of the OLED display module, when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above.



12.3 Designing Precautions

- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, panel damage may be happen.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD). (Recommend value: 0.5A)

(4) Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices.

- (5) As for EMI, take necessary measures on the equipment side basically.
- (6) When fastening the OLED display module, fasten the external plastic housing section.
- (7) If power supply to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module. Connection (contact) to any other potential than the above may lead to rupture of the IC.



Page: 1

Module Sample Estimate Feedback Sheet Module Number : **1** • Panel Specification : □NG , 1. Panel Type : □ Pass □NG ,_____ 2. Numbers of Pixel : □ Pass □NG ,_____ 3. View Area : □ Pass □NG ,_____ 4. Active Area : □ Pass □NG ,_____ D Pass 5.Emitting Color : □NG , □Pass 6.Uniformity : □NG ,____ 7.Operating Pass Temperature : □NG ,___ 8.Storage Temperature : - Pass 9.Others : **2** • Mechanical Specification : 1. PCB Size : □Pass □NG ,___ □NG , 2.Frame Size : □Pass □NG , 3.Materal of Frame : □Pass □NG , 4.Connector Position : □Pass □NG , 5.Fix Hole Position : □Pass □NG ,____ 6. Thickness of PCB : □Pass 7. Height of Frame to □Pass □NG ,____ PCB: □NG ,_____ 8.Height of Module : □Pass □NG , 9.Others : Pass 3 · <u>Relative Hole Size</u>: □NG ,____ 1.Pitch of Connector : □Pass 2.Hole size of □Pass □NG ,_____ Connector : □NG ,_____ □Pass 3.Mounting Hole size : □NG ,_____ 4.Mounting Hole Type : □Pass □Pass 5.Others : □NG ,

>> Go to page 2 <<



Page: 2

Module Number :								
4 · Electronic Characteristics of Module								
1.Input Voltage :	□Pass	□NG ,						
2.Supply Current :	□Pass	□NG ,						
3.Driving Voltage for OLED :	□Pass	□NG ,						
4.Contrast for OLED :	□Pass	□NG ,						
5.Negative Voltage Output :	□Pass	□NG ,						
6.Interface Function :	□Pass	□NG ,						
7.ESD test :	□Pass	□NG ,						
8.Others :	□Pass	□NG ,						
E Summany'								

5 · <u>Summary</u> :

Sales signature : _____ Customer Signature : _____

Date :